

<b>Notice of References Cited</b>	Application/Control No. 10/691,240	Applicant(s)/Patent Under Reexamination KIM ET AL.	
	Examiner Mai-Huong Tran	Art Unit 2818	Page 1 of 1

**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-6,576,493	06-2003	Lin et al.	438/107
	B	US-			
	C	US-			
	D	US-			
	E	US-			
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

**FOREIGN PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Warner et al., Methods of Making Microelectronic Assemblies Including Folded Substrates, Pub. No. US 2003/0168725.
	V	Primavera et al., Method and Apparatus for Mounting and Packaging Electronic Components, Pub. No. US 2002/0044423.
	W	
	X	

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.